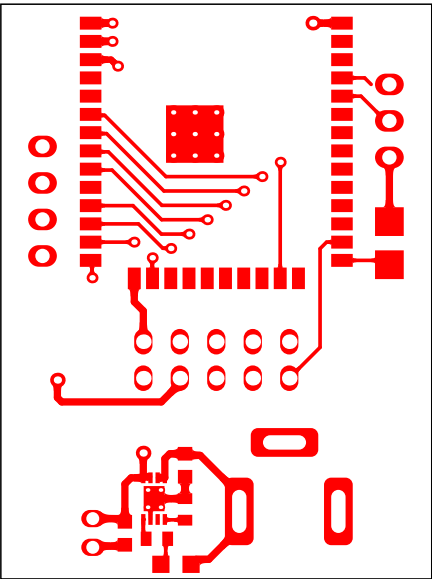
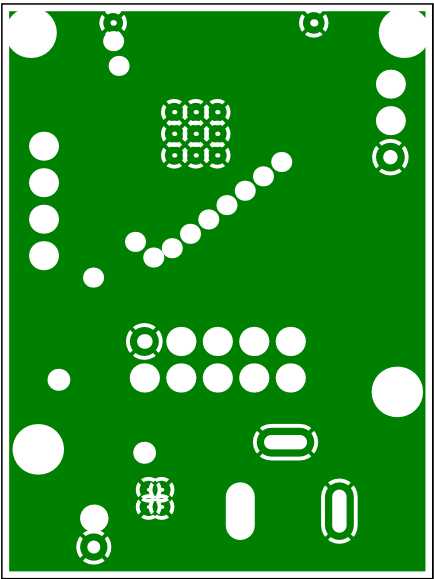


Motherboard Bracelet

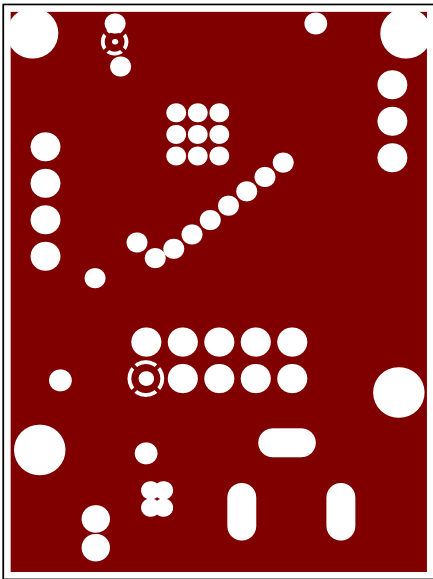
Top Layer (Scale 1.9:1)



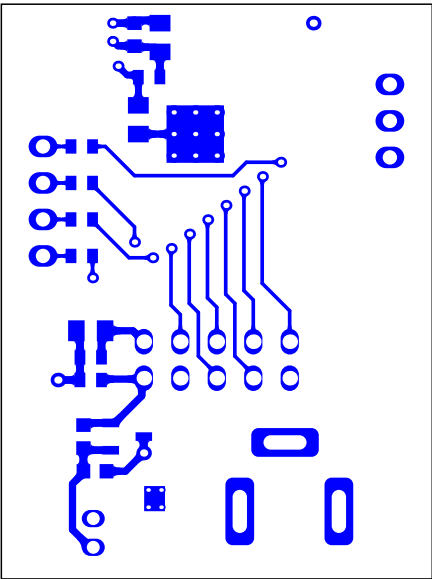
GroundPlane (Scale 1.9:1)



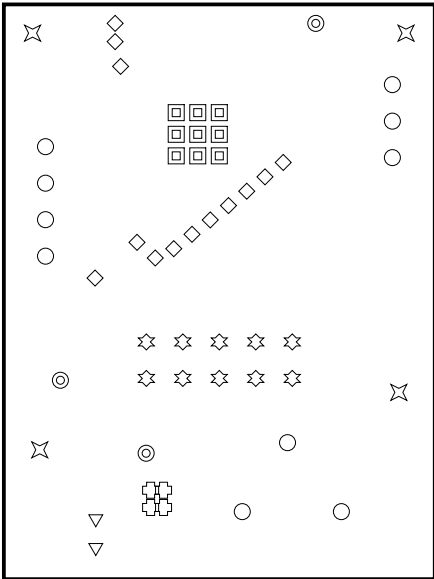
VccPlane (Scale 1.9:1)



Bottom Layer (Scale 1.9:1)



Drill Drawing View (Scale 1.9:1)



Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.01mm	Solder Resist	Solder Mask	GTS
Copper	Top Layer	0.04mm		Signal	GTL
Prepreg		0.22mm	PP-023	Dielectric	
CF-004	GroundPlane	0.04mm		Internal Plane	GP1
Core		0.99mm	Core-042	Dielectric	
CF-004	VccPlane	0.04mm		Internal Plane	GP2
Prepreg		0.22mm	PP-023	Dielectric	
Copper	Bottom Layer	0.04mm		Signal	GBL
Surface Material	Bottom Solder	0.01mm	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.59mm					

Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
⊕	4	0.25mm	Plated	
⊞	9	0.30mm	Plated	
◇	13	0.38mm	Plated	
◎	3	0.51mm	Plated	
▽	2	0.90mm	Plated	
○	10	1.00mm	Plated	
☆	10	1.02mm	Plated	
✧	4	2.50mm	Plated	
	55 Total			



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Projeto				Motherboard Bracelet							
Elaboração		Roger		Aprovação		Marlio		Layout		Natan Figueiredo	
Código				Revisão		R00		Folha		1/1	
Data		4/4/2024		Horário		2:35 AM		Tamanho		A3	
Arquivo		Y:\GIT\WF_Tecnologia\Roger_Lakoski_Mestrado\RL_Motherboard_Bra									

Revisão	Data	Responsável	Histórico
R00	17/02/202	Natan MF	=HIST01
			=HIST02
			=HIST03
			=HIST04